- **Full-Carry Look-Ahead Across the Four Bits**

- **Systems Achieve Partial Look-Ahead Performance With the Economy of Ripple Carry**

- **Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs**

SN54F283 . . . J PACKAGE
SN74F283 . . . D OR N PACKAGE
(TOP VIEW)

```
        ___  ___
Σ2  [ 1      16 ]  V_CC
B2  [ 2      15 ]  B3
A2  [ 3      14 ]  A3
Σ1  [ 4      13 ]  Σ3
A1  [ 5      12 ]  A4
B1  [ 6      11 ]  B4
C0  [ 7      10 ]  Σ4
GND [ 8       9 ]  C4
```

SN54F283 . . . FK PACKAGE
(TOP VIEW)

```
         B2  Σ2  NC  V_CC  B3
          3   2   1   20   19
A2 [ 4                        18 ] A3
Σ1 [ 5                        17 ] Σ3
NC [ 6                        16 ] NC
A1 [ 7                        15 ] A4
B1 [ 8                        14 ] B4
          9  10  11  12  13
         C0 GND  NC  C4  Σ4
```

NC – No internal connection

description

The ′F283 is a full adder that performs the addition of two 4-bit binary words. The sum (Σ) outputs are provided for each bit and the resultant carry (C4) output is obtained from the fourth bit.
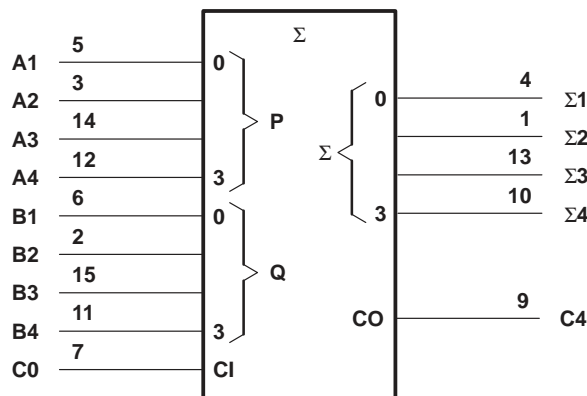
The device features full internal look-ahead across all four bits generating the carry term C4 in typically 5.7 ns. This capability provides the system designer with partial look-ahead performance at the economy and reduced package count of a ripple-carry implementation.

The adder logic, including the carry, is implemented in its true form. End-around carry can be accomplished without the need for logic or level inversion.

The ′F283 can be used with either all-active-high (positive logic) or all-active-low (negative logic) operands.
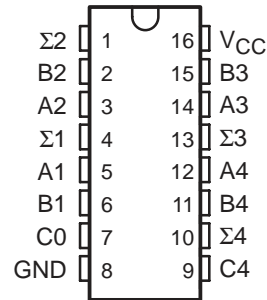
The SN54F283 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74F283 is characterized for operation from 0°C to 70°C.
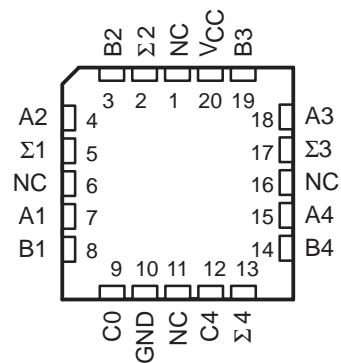
logic symbol†

† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, J, and N packages.

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POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

POST OFFICE BOX 1443 ● HOUSTON, TEXAS 77251–1443

logic diagram (positive logic)

Pin numbers shown are for the D, J, and N packages.

FUNCTION TABLE

INPUTS				OUTPUTS					
				WHEN C0 = L			WHEN C0 = H		
				WHEN C2 = L			WHEN C2 = H		
A1	B1	A2	B2	$\Sigma1$	$\Sigma2$	C2	$\Sigma1$	$\Sigma2$	C2
A3	B3	A4	B4	$\Sigma3$	$\Sigma4$	C4	$\Sigma3$	$\Sigma4$	C4
L	L	L	L	L	L	L	H	L	L
H	L	L	L	H	L	L	L	H	L
L	H	L	L	H	L	L	L	H	L
H	H	L	L	L	H	L	H	H	L
L	L	H	L	L	H	L	H	H	L
H	L	H	L	H	H	L	L	L	H
L	H	H	L	H	H	L	L	L	H
H	H	H	L	L	L	H	H	L	H
L	L	L	H	L	H	L	H	H	L
H	L	L	H	H	H	L	L	L	H
L	H	L	H	H	H	L	L	L	H
H	H	L	H	L	L	H	H	L	H
L	L	H	H	L	L	H	H	L	H
H	L	H	H	H	L	H	L	H	H
L	H	H	H	H	L	H	L	H	H
H	H	H	H	L	H	H	H	H	H

NOTE: Input conditions at A1, B1, A2, B2, and C0 are used to determine outputs $\Sigma1$ and $\Sigma2$ and the value of the internal carry C2. The values at C2, A3, B3, A4, and B4 are then used to determine outputs $\Sigma3$, $\Sigma4$, and C4.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} .... −0.5 V to 7 V
Input voltage range (see Note 1) .... −1.2 V to 7 V
Input current range .... −30 mA to 5 mA
Voltage range applied to any output in the high state .... −0.5 V to V_{CC}
Current into any output in the low state .... 40 mA
Operating free-air temperature range: SN54F283 .... −55°C to 125°C
⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀⠀SN74F283 .... 0°C to 70°C
Storage temperature range .... −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1:   The input voltage ratings may be exceeded provided the input current ratings are observed.

SN54F283, SN74F283
4-BIT BINARY FULL ADDERS
WITH FAST CARRY
SDFS069A – D2932, MARCH 1987 – REVISED OCTOBER 1993

recommended operating conditions

		SN54F283			SN74F283			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{IK}	Input clamp current			−18			−18	mA
I_{OH}	High-level output current			− 1			− 1	mA
I_{OL}	Low-level output current			20			20	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54F283			SN74F283			UNIT
				MIN	TYP[†]	MAX	MIN	TYP[†]	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = − 18 mA			−1.2			−1.2	V
V_{OH}		V_{CC} = 4.5 V	I_{OH} = − 1 mA	2.5	3.4		2.5	3.4		V
		V_{CC} = 4.75 V,	I_{OH} = − 1 mA				2.7			
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 20 mA		0.3	0.5		0.3	0.5	V
I_I		V_{CC} = 5.5 V,	V_I = 7 V			0.1			0.1	mA
I_{IH}		V_{CC} = 5.5 V,	V_I = 2.7 V			20			20	µA
I_{IL}	Any A or B	V_{CC} = 5.5 V,	V_I = 0.5 V			− 1.2			− 1.2	mA
	C0					− 0.6			− 0.6	
I_{OS}[‡]		V_{CC} = 5.5 V,	V_O = 0	−60		−150	−60		−150	mA
I_{CC}		V_{CC} = 5.5 V,	V_I = 4.5 V		36	55		36	55	mA

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[‡] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, C_L = 50 pF, R_L = 500 Ω, T_A = 25°C			V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 500 Ω, T_A = MIN to MAX[§]				UNIT
			'F283			SN54F283		SN74F283		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	C0	Σ	2.7	6.6	9.5	2.7	14	2.7	10.5	ns
t_{PHL}			3.2	6.6	9.5	3.2	14	3.2	10.5	
t_{PLH}	A or B	Σ	3.2	6.6	9.5	3.2	14	3.2	10.5	ns
t_{PHL}			2.7	6.6	9.5	2.7	14	2.7	10.5	
t_{PLH}	C0	C4	2.7	5.3	7.5	2.7	10.5	2.7	8.5	ns
t_{PHL}			2.2	5	7	2.2	10	2.2	8	
t_{PLH}	A or B	C4	2.7	5.3	7.5	2.7	10.5	2.7	8.5	ns
t_{PHL}			2.2	4.9	7	2.2	10	2.2	8	

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: Load circuits and waveforms are shown in Section 1.

![Texas Instruments logo]

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9758701Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9758701Q2A SNJ54F 283FK	Samples
5962-9758701QEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9758701QE A SNJ54F283J	Samples
5962-9758701QEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9758701QE A SNJ54F283J	Samples
JM38510/34201B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 34201B2A	Samples
JM38510/34201B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 34201B2A	Samples
JM38510/34201BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 34201BEA	Samples
JM38510/34201BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 34201BEA	Samples
JM38510/34201BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 34201BFA	Samples
JM38510/34201BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 34201BFA	Samples
M38510/34201B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 34201B2A	Samples
M38510/34201B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 34201B2A	Samples
M38510/34201BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 34201BEA	Samples
M38510/34201BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 34201BEA	Samples
M38510/34201BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 34201BFA	Samples
M38510/34201BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 34201BFA	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN54F283J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54F283J	Samples
SN54F283J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54F283J	Samples
SN74F283D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN74F283N	Samples
SN74F283N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN74F283N	Samples
SNJ54F283FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9758701Q2A SNJ54F 283FK	Samples
SNJ54F283FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9758701Q2A SNJ54F 283FK	Samples
SNJ54F283J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9758701QE A SNJ54F283J	Samples
SNJ54F283J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9758701QE A SNJ54F283J	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54F283, SN74F283 :

● Catalog: SN74F283

● Military: SN54F283

NOTE: Qualified Version Definitions:
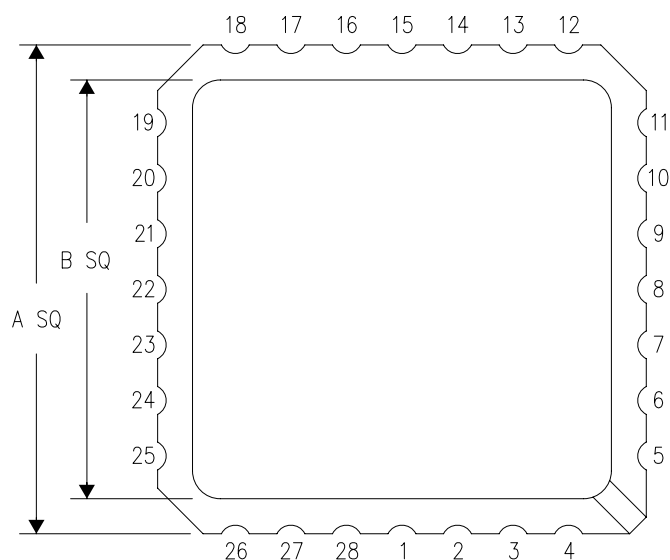
   ● Catalog - TI's standard catalog product

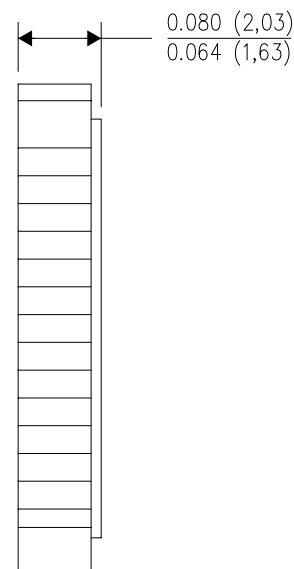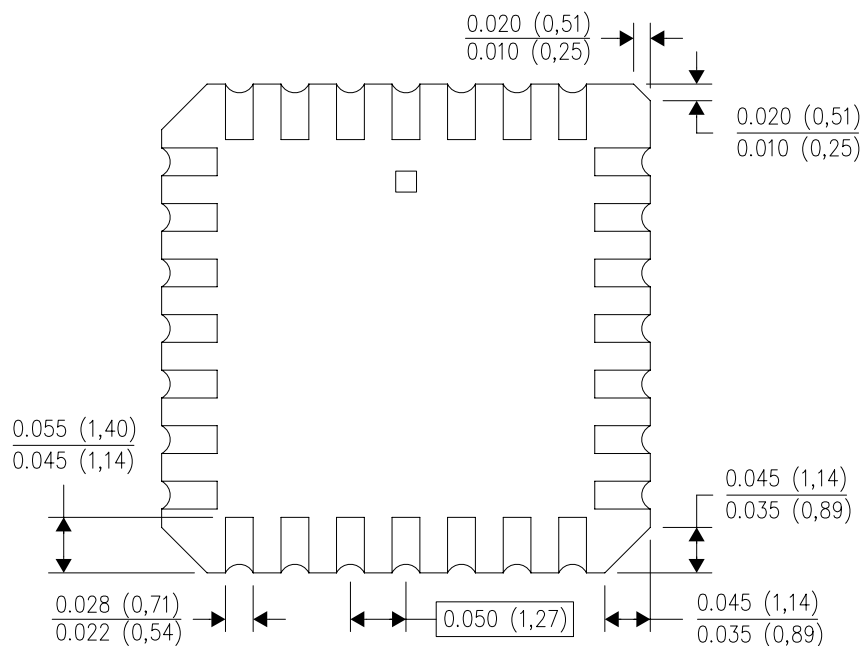   ● Military - QML certified for Military and Defense Applications

FK (S−CQCC−N**)   LEADLESS CERAMIC CHIP CARRIER
28 TERMINAL SHOWN

NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

0.020 (0,51) / 0.010 (0,25)

0.020 (0,51) / 0.010 (0,25)

0.080 (2,03) / 0.064 (1,63)

0.055 (1,40) / 0.045 (1,14)

0.045 (1,14) / 0.035 (0,89)

0.028 (0,71) / 0.022 (0,54)

0.050 (1,27)

0.045 (1,14) / 0.035 (0,89)

4040140/D 01/11

NOTES: A.   All linear dimensions are in inches (millimeters).
          B.   This drawing is subject to change without notice.
          C.   This package can be hermetically sealed with a metal lid.
          D.   Falls within JEDEC MS−004
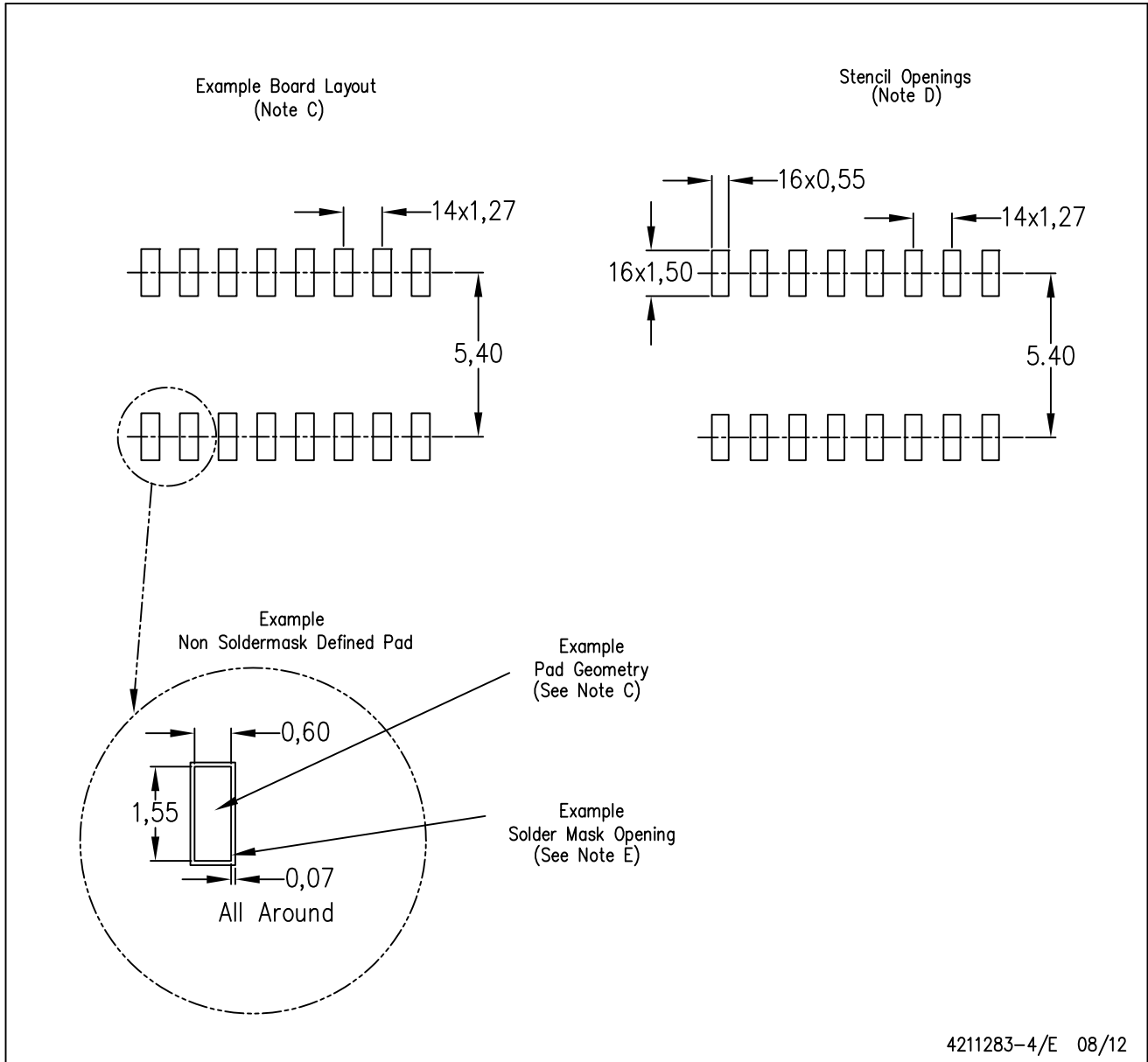
D (R−PDSO−G16)   PLASTIC SMALL OUTLINE
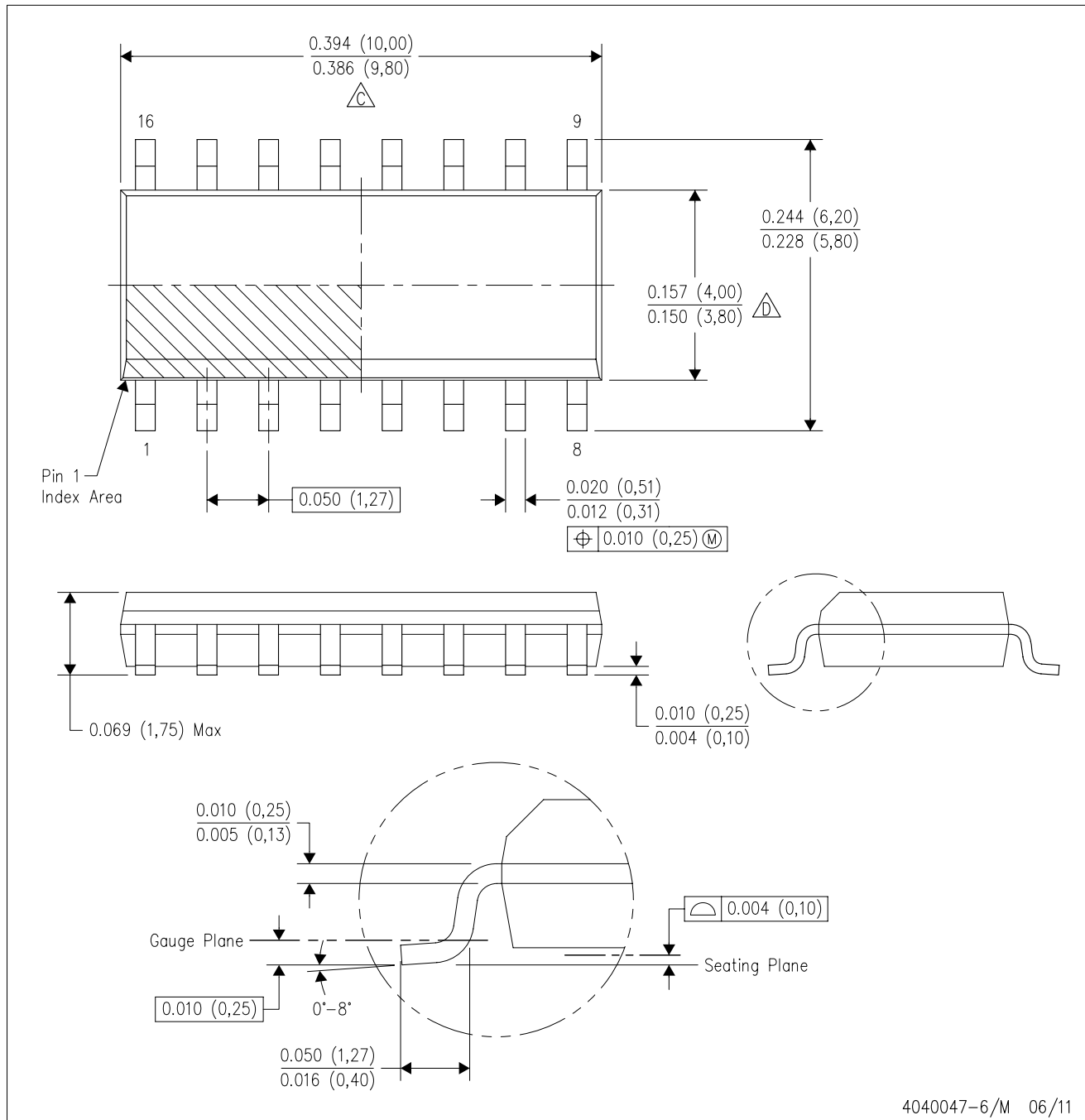
0.394 (10,00)
0.386 (9,80)
⚠C⚠

16   9

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80) ⚠D⚠

1   8

Pin 1
Index Area

0.050 (1,27)   0.020 (0,51)
                                0.012 (0,31)

⊕ | 0.010 (0,25) | Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

◁ | 0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−6/M   06/11

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
      ⚠C⚠   Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
              not exceed 0.006 (0,15) each side.
      ⚠D⚠   Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
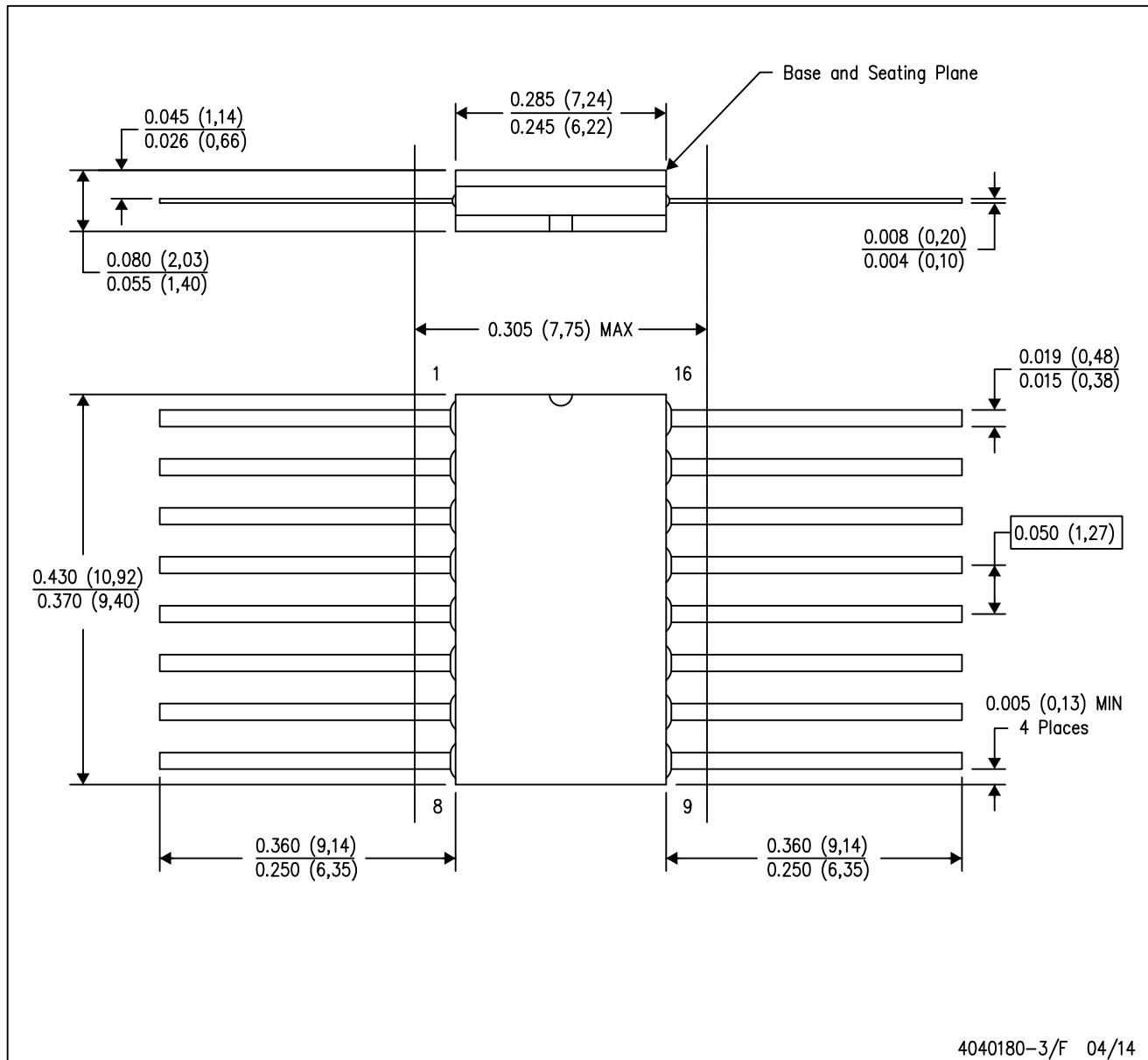   E.   Reference JEDEC MS−012 variation AC.

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D (R−PDSO−G16)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

←14x1,27

16x0,55

14x1,27

16x1,50

5,40

5.40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

1,55

Example
Solder Mask Opening
(See Note E)

0,07

All Around

4211283−4/E 08/12

NOTES: A. All linear dimensions are in millimeters.
          B. This drawing is subject to change without notice.
          C. Publication IPC−7351 is recommended for alternate designs.
          D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
          E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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W (R−GDFP−F16)   CERAMIC DUAL FLATPACK

0.045 (1,14)
0.026 (0,66)

0.285 (7,24)
0.245 (6,22)

Base and Seating Plane

0.008 (0,20)
0.004 (0,10)

0.080 (2,03)
0.055 (1,40)

0.305 (7,75) MAX

1   16

0.019 (0,48)
0.015 (0,38)

0.430 (10,92)
0.370 (9,40)

0.050 (1,27)

0.005 (0,13) MIN
4 Places

8   9

0.360 (9,14)
0.250 (6,35)

0.360 (9,14)
0.250 (6,35)

4040180−3/F   04/14

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package can be hermetically sealed with a ceramic lid using glass frit.
         D.   Index point is provided on cap for terminal identification only.
         E.   Falls within MIL STD 1835 GDFP2−F16

J (R—GDIP—T**)   CERAMIC DUAL IN—LINE PACKAGE
14 LEADS SHOWN

DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	——	——	——	——
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

1   7

0.065 (1,65)
0.045 (1,14)

C

0.005 (0,13) MIN

0.060 (1,52)
0.015 (0,38)

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

0.026 (0,66)
0.014 (0,36)

0.100 (2,54)

A

0°—15°

0.014 (0,36)
0.008 (0,20)

4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. This package is hermetically sealed with a ceramic lid using glass frit.
        D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
        E. Falls within MIL STD 1835 GDIP1—T14, GDIP1—T16, GDIP1—T18 and GDIP1—T20.

N (R−PDIP−T**) PLASTIC DUAL−IN−LINE PACKAGE

16 PINS SHOWN
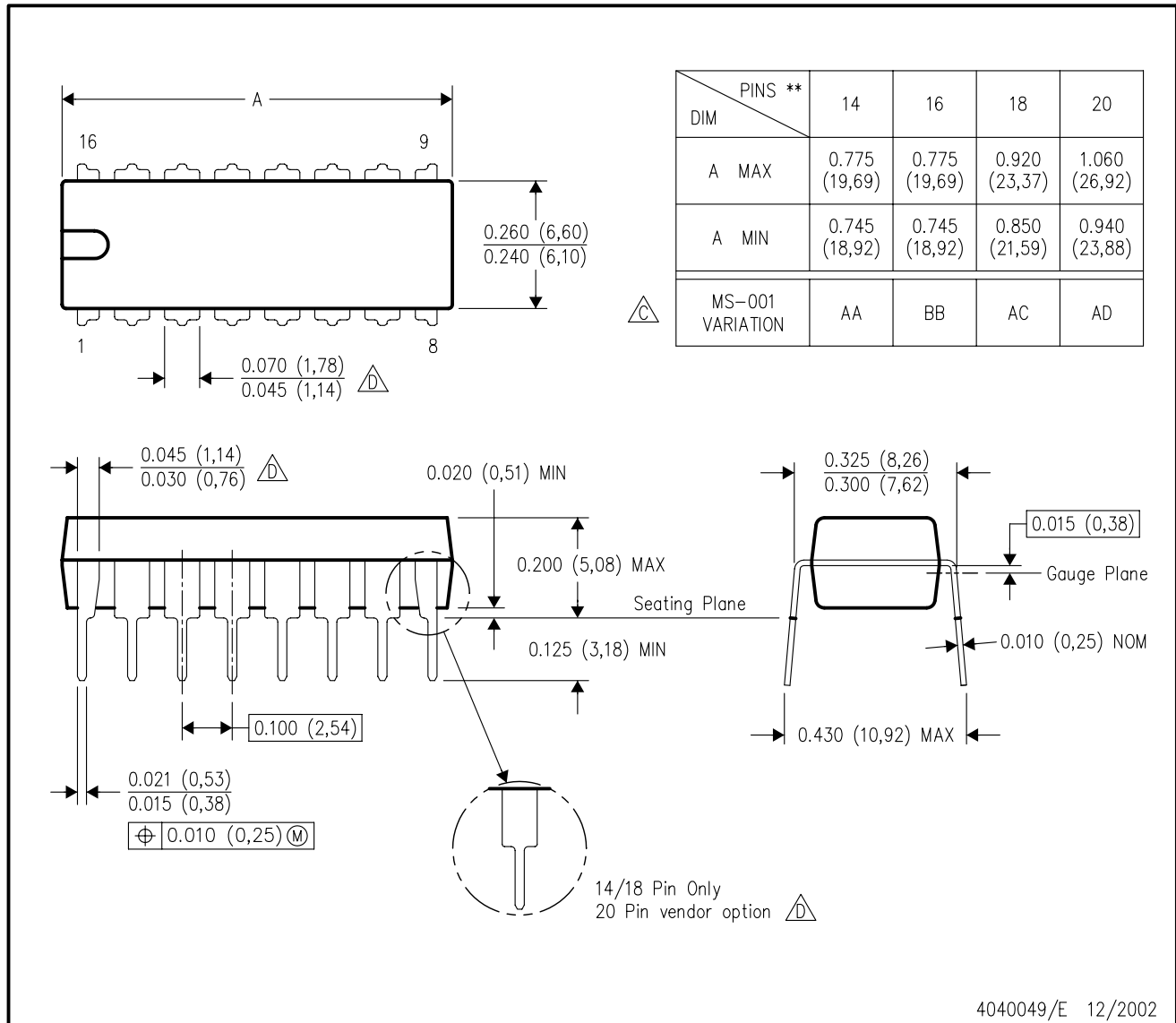
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS−001 VARIATION	AA	BB	AC	AD

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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